Technical Data Sheet

KES-3070

Biphenyl aralkyl type epoxy

General Description

KES-3070在CCL配方中使用時,具有出色的熱穩定性和自體阻燃特性。KES-3070具有低軟化點和高流動性,使用者可添加大量無機填料,以提高最終產品的機械性和熱穩定性。KES-3070的低吸濕性使得最終產品在潮濕條件下更可靠。

Resin Properties

Property	Typical values
EEW(g/eq)	270~310
Hy-CI(ppm)	500 max.
Softening point(℃) (Ball˚,5℃/min.)	65~75
Melt viscosity (P) (ICI, 150℃)	2.0~4.0

Characteristics

- Excellent thermal stability when cured with proper curing agent
- 2. Low moisture uptake in humid condition
- 3. Low softening point (< 80°C) and melt viscosity
- 4. Excellent toughness for severe mechanical process

Storage

Keep in cool, dry, ventilate condition and in closed containers.

Keep away from heat sources and direct sunlight. Recommended safe handing procedures are discussed in the information on the MSDS should reviewed and understood before working.

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	Properties	KES-3070	Competitor's
Resin Properties	Softening point (°C) ¹⁾	66.7	69.0
	Mw (g/mol)	1810	1880
	EEW (g/eq)	291.1	289.5
	Hy-Cl (ppm)	280.1	290.5
	Viscosity (Pa.s) ²⁾	0.27	0.31

¹⁾ Ball & ring. 5°C/min. 2) ICI viscometer, 150°C

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